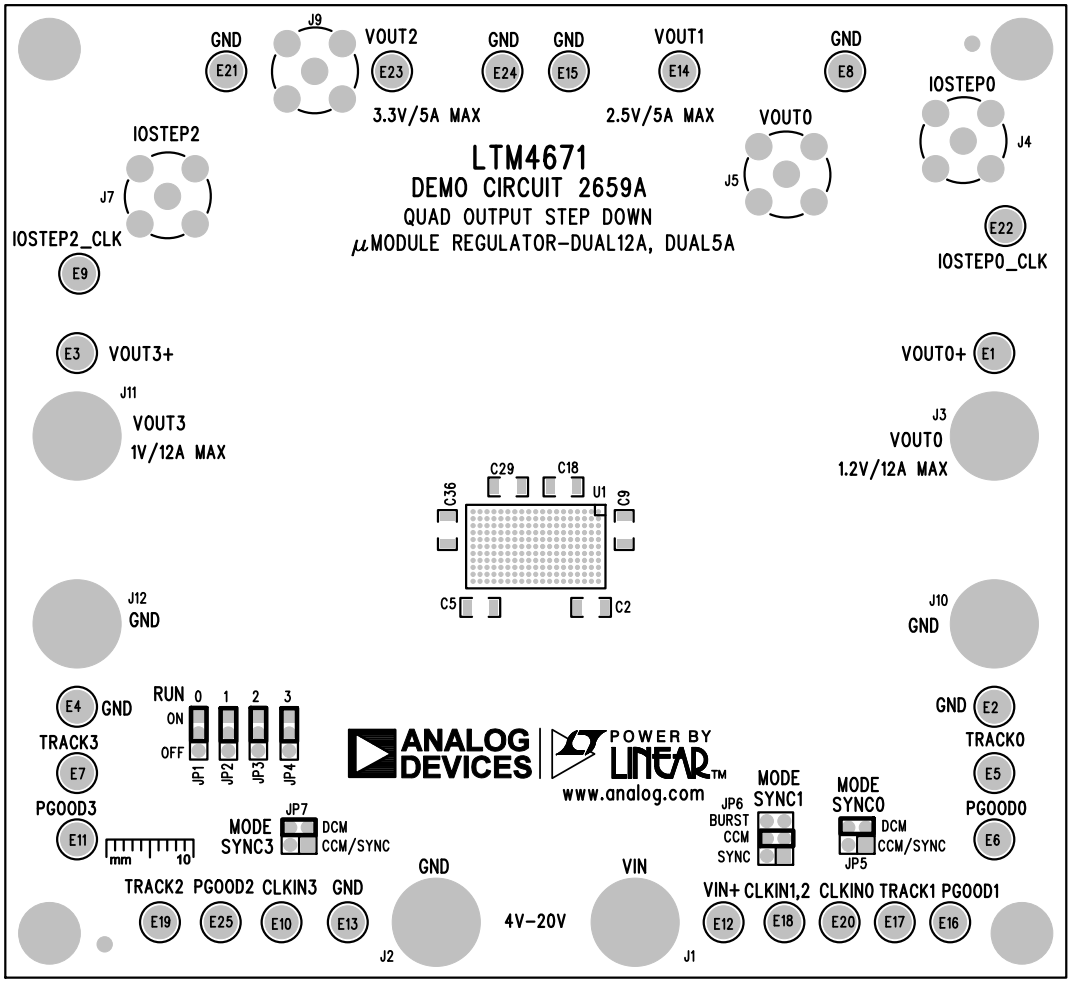
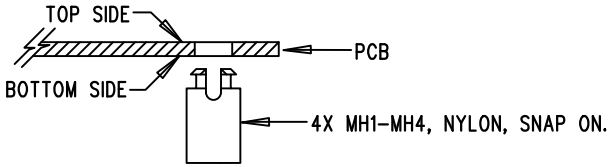
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	4	PRODUCTION	SAM Y.	06-06-18



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT SHOWN BELOW:



APPROVALS	
PCB DES.	LT
APP ENG.	SY
SCALE = NONE	

ANALOG DEVICES | POWER BY LINEAR™

FOR ADI CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING
QUAD OUTPUT STEP DOWN
μMODULE REGULATOR-DUAL12A, DUAL5A

SIZE	IC NO.	REV.
N/A	LTM4671EY DEMO CIRCUIT 2659A	4

FILENAME: DC2659A-4.PCB | SHT 1 OF 2